

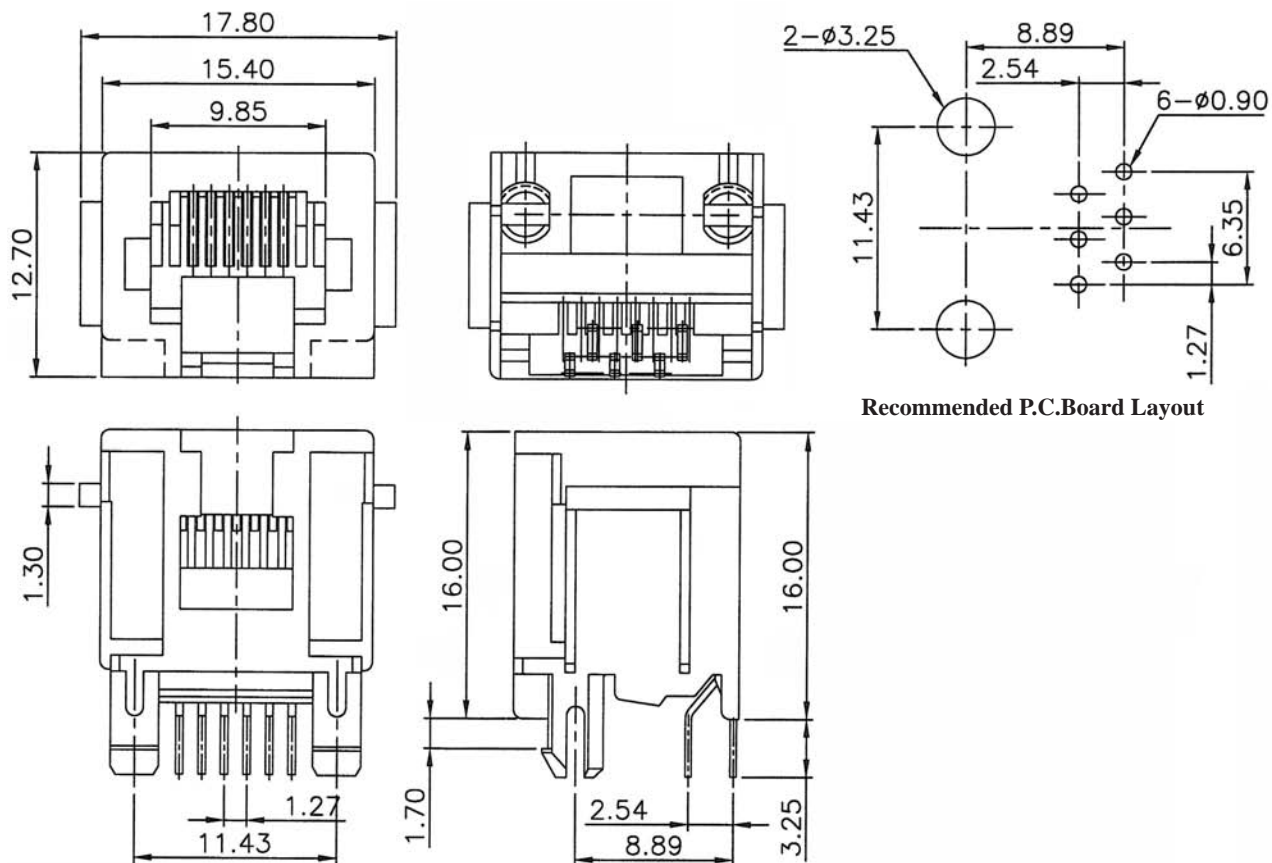
TOP ENTRY MODULAR PCB JACK 6P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N MJ 3 6 - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: WITH PANEL STOP

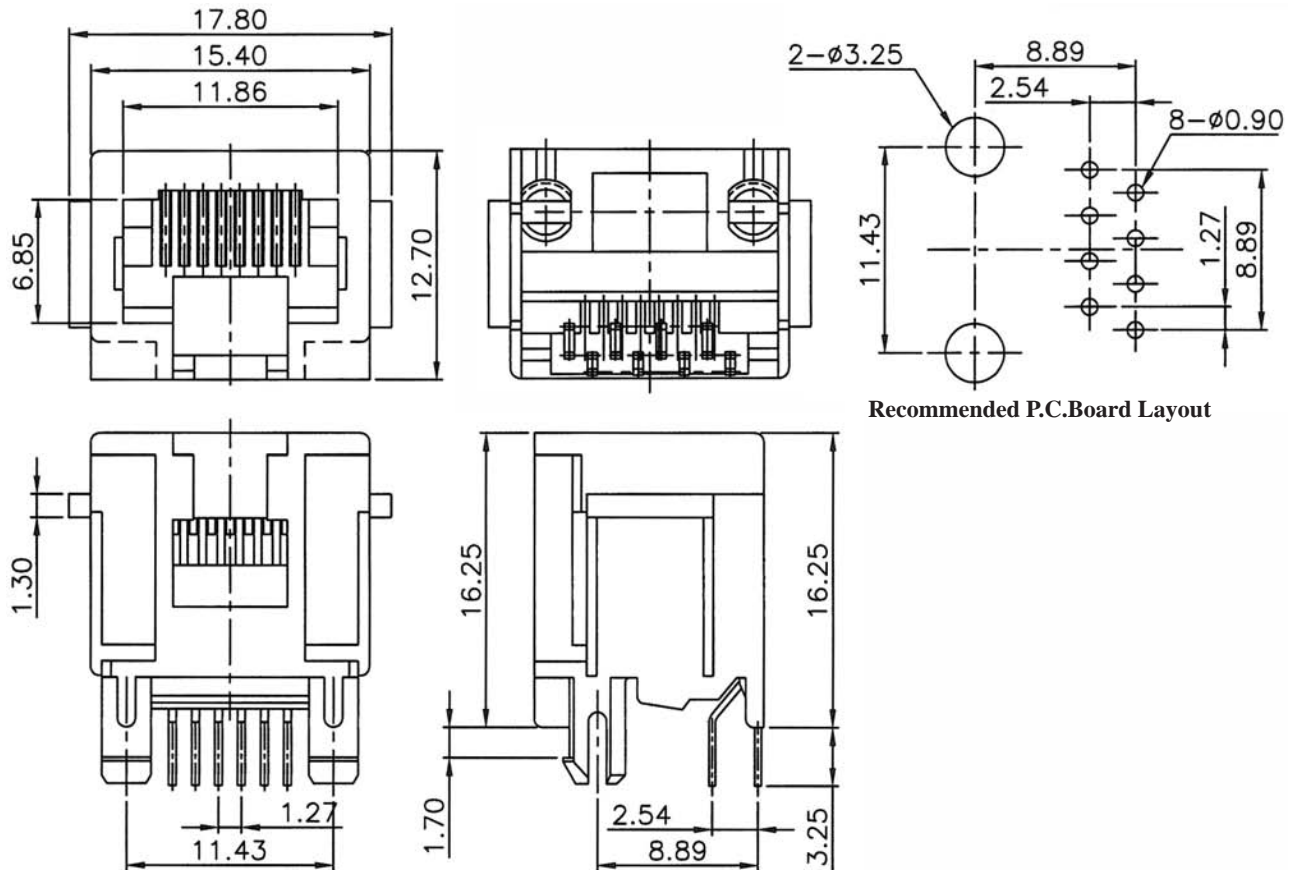
TOP ENTRY MODULAR PCB JACK 8P PROFILE=16.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N MJ 3 6 - $\frac{x}{1}$ $\frac{x}{2}$ B

- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: WITH PANEL STOP